



Title of Change:	Qualification of Sumitomo mold compound from G700HC to G700HF
Proposed first ship date:	25 February 2016
Contact information:	Contact your local ON Semiconductor Sales Office or Mohd Hezri Abu Bakar <MohdHezri.AbuBakar@onsemi.com>
Samples:	Contact your local ON Semiconductor Sales Office or Ahmad Faris Dzulkipli <AhmadFaris.Dzulkipli@onsemi.com>
Additional Reliability Data:	Contact your local ON Semiconductor Sales Office or Chean Ching Sim <cheanching.sim@onsemi.com>
Type of notification:	This is a Final Product/Process Change Notification (FPCN) sent to customers. FPCNs are issued 12 months prior to implementation of the change. ON Semiconductor will consider this change approved unless specific conditions of acceptance are provided in writing within 30 days of receipt of this notice. To do so, contact <PCN.Support@onsemi.com>.
Change Part Identification:	Affected parts will be identified with a date code of WW20'15 or later

Change category(s):

- | | | |
|---|---|---|
| <input type="checkbox"/> Wafer Fab Change | <input type="checkbox"/> Manufacturing Site Change/Addition | <input type="checkbox"/> Product specific change |
| <input type="checkbox"/> Assembly Change | <input type="checkbox"/> Manufacturing Process Change | <input type="checkbox"/> Datasheet/Product Doc change |
| <input type="checkbox"/> Test Change | <input checked="" type="checkbox"/> Material Change | <input type="checkbox"/> Shipping/Packaging/Marking |
| | | <input type="checkbox"/> Other: _____ |

Sites Affected:

- All site(s) not applicable
 ON Semiconductor site(s) :
 External Foundry/Subcon site(s):

Site 1
ON Seremban, Malaysia

Site 2

Description and Purpose:

To notify customers of the change in mold compound on selected devices in DPAK package from Sumitomo G700HC to G700HF. The change is to improve delamination at post area.

Reliability Data Summary:

#	Test	Name	Test Condition	Read points	NTDV20N06T4G	NVD5490NLT4G	NVD5117PLT4G	NVD6824NLT4G
1	AC-PC	Autoclave + PC	121°C/100% RH/15psig	96 Hrs	NA	0/84	0/84	0/84
2	TC-PC	Temperature Cycling + PC	Ta = -55/150° C	1000 Cyc	0/84	0/84	0/84	0/84
3	UHAST-PC	Unbias High Accelerated Stress Test + PC	121°C/100% RH/15psig	96 Hrs	0/84	NA	NA	NA
4	HAST-PC	Highly Accelerated Stress Test + PC	Ta= +130° C, RH = 85%, PSIG= 18.8,	96 Hrs	NA	NA	0/84	NA
5	H3TRB – PC	High Humidity High Temp Rev Bias + Preconditioning	Ta=85°C, 85% RH, 80% rated or 100V max	1008 Hrs	0/84	0/84	NA	0/84
6	IOL-PC	Intermittent Operating Life + PC	Ta=+25°C, delta Tj=100°C	15000 Cyc	0/84	0/84	0/84	0/84
7	HTRB	High Temp Reverse Bias	TA = 175°C	1008 Hrs	0/84	0/84	0/84	0/84
8	HTGB	High Temp Gate Bias	TA = 175°C	1008 Hrs	0/84	0/84	0/84	0/84
9	HTSL	High Temperature Storage Life	Ta = 175° C	1008 Hrs	0/84	0/84	0/84	0/84
10	RSH	Resistance to Solder Heat	260 C Immersion	Result	0/30	0/30	0/30	0/30

**Electrical Characteristic Summary:**

No changes in electrical characteristics. All electrical performance meets the current datasheet specifications.

List of affected Standard Parts:

NTDV5804NT4G	NVD5867NLT4G
NVD4804NT4G	NVD5890NT4G
NVD4808NT4G	NVD6820NLT4G
NVD4810NT4G	NVD6824NLT4G
NVD5117PLT4G	NVD6828NLT4G
NVD5802NT4G	SVD5804NT4G
NVD5803NT4G	NVD5863NLT4G
NVD5806NT4G	NVD5865NLT4G
NVD5807NT4G	NVD5862NT4G